Materials Declaration Form

IPC **Form Type ***	1752 Distribute	**Version**	2
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2016-04-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	**Representative Title**	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
Floriana San Biagio
Date: 2016.04.18
10:45:29 +02:00

Product

Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	NDO7*27025AW	A	BO2A	2016-04-18
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	80.00	mg	Each	ECOPACK® 3
,	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information

J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: O7 SO 08 .15 JEDEC; MDF valid for TS272BIDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**

QueryList : REACH-17th December 2015				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**NDO7*27025AW**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	1.566	mg	supplier	die	Silicon (Si)	7440-21-3		1.527	mg	975096	19088
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	3831	75
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2554	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	18519	363
Leadframe	Copper & its alloys	30.328	mg	supplier	alloy	Copper (Cu)	7440-50-8		30.072	mg	991559	375900
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	495	188
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	791	300
				supplier	metallization	Silver (Ag)	7440-22-4		0.217	mg	7155	2713
Die attach	Other Organic Materials	0.584	mg	supplier	glue	Silver (Ag)	7440-22-4		0.514	mg	880137	6425
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.029	mg	49658	363
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.029	mg	49658	363
				supplier	glue	Acrylate polymer	87320-05-6		0.012	mg	20548	150
Bonding wires	Other inorganic materials	0.065	mg	supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	813
Encapsulation	Other Organic Materials	46.399	mg	supplier	mold compound	Silica, vitreous	60676-86-0		40.692	mg	877002	508650
				supplier	mold compound	Epoxy resin	85954-11-6		1.856	mg	40001	23200
				supplier	mold compound	Epoxy	29690-82-2		1.856	mg	40001	23200
				supplier	mold compound	phenol resin	Proprietary		1.392	mg	30001	17400
				supplier	mold compound	additive	Proprietary		0.464	mg	10000	5800
				supplier	mold compound	carbon black	1333-86-4		0.139	mg	2996	1738
connections coating	Solder	1.058	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.058	mg	1000000	13225